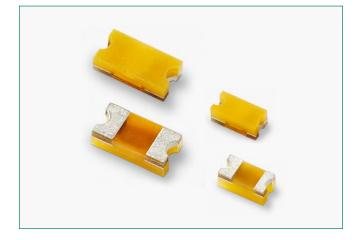


XGD Series



#### **Equivalent Circuits**



Life Support Note:

Not Intended for Use in Life Support or Life Saving Applications The products shown herein are not designed for use in life sustaining or life saving applications unless otherwise expressly indicated.

#### **Product Characteristics**

Part Number	Lines Protected	Component Package	Available as Halogen-Free
XGD10402	1	0402	Yes
XGD10603	1	0603	Yes

#### Description

XTREME-GUARD<sup>™</sup> ESD Suppressors protect sensitive electronic equipment against extreme ESD conditions, in very small 0402 and 0603 footprints. This series product is specifically designed to suppress fast-rising ESD transients up to 30kV while adding virtually no capacitance to the circuit, which helps preserve signal integrity and minimize data loss. It is a RoHS compliant, halogen free, and Pb free ESD Suppressor.

## Features

- High ESD Rating up to 30kV Contact/Air Discharge
- RoHS compliant, lead-free and halogen-free
- Ultra-low capacitance
- Low leakage current
- Fast response time
- Bi-directional
- Withstands multiple ESD strikes
- Compatible with pick-and-place processes
  Available in 1000, 5000,

P0 HF

RoHS

- and 10000 piece reels (EIA-RS481)
- High rated voltage up to 32V maximum
- High operating temperature at 125°C

# Applications

- Wearable Devices
- Notebooks/Laptops/PCs
- Gaming Consoles
- Smart TVs
- Smart Phones
- Tablets

- Set Top Boxes
- Networking and Wireless Hardware
- Stationary and Portable Medical Devices

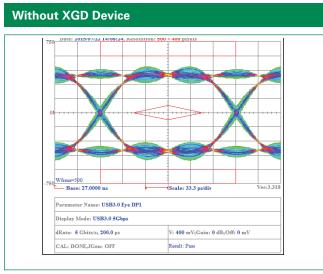
# **Electrical Characteristics**

Specification	XGD10402	XGD10603	Notes
ESD Capability: IEC 61000-4-2 Contact Discharge (typical) IEC 61000-4-2 Air Discharge (typical)	30kV 30kV	30kV 30kV	The ESD capability measured by direct and air discharge method is subject to testing equipment and conditions. Numerous factors could affect the reliability and reproducibility of the direct and air discharge test results.
Trigger Voltage (typical) Clamping Voltage (typical)	250V 40V	400V 40V	Measured per IEC 61000-4-2 8kV Direct Discharge Method
Trigger Voltage (typical) Clamping Voltage (typical)	150V 40V	300V 28V	Measured using 500V TLP Direct Discharge Method
Rated Voltage (maximum)	24V max	32V max	
Capacitance (typical)	0.04 pF	0.09 pF	Measured at 250MHz
ResponseTime	<1nS	<1nS	
Leakage Current (typical)	<1nA @24V	<1nA @24V	
ESD Pulse Withstand	1000 pulses min	1000 pulses min	Some shifting in characteristics may occur when tested over multiple pulses at a very rapid rate

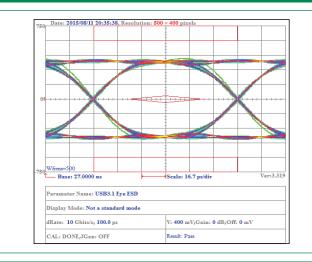
Note: Testing performed on Littelfuse test setup as described in Typical Test Setup Section on page 4 of this document.



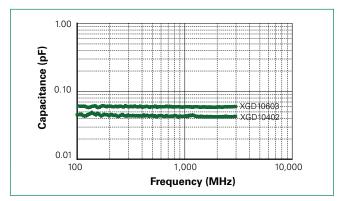
# Signal Integrity: USB3.0 5Gbps



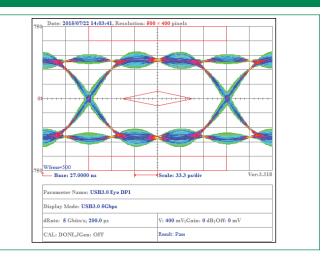
# Signal Integrity: USB3.1 10Gbps



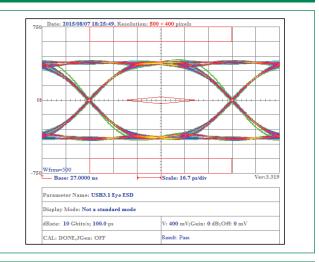
# **Typical Device Capacitance**



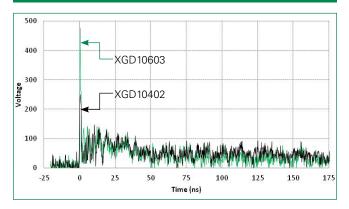
# With XGD Device



# With XGD Device



# Typical ESD Response



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# Without XGD Device



# **Physical Specifications**

Materials Body: Glass Epoxy Terminations: Copper/Nickel/Tin	
Solderability	MIL-STD-202, Method 208
Soldering Parameters	Wave solder - 260°C, 10 seconds maximum Reflow solder - 260°C, 30 seconds maximum

#### **Environmental Specifications**

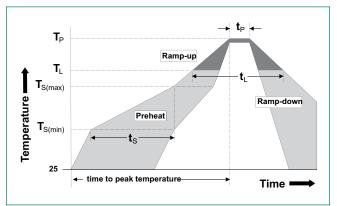
Operating and Storage Temperature	-65°C to +125°C	
Moisture Resistance	0402 and 0603 series: 85°C, 85% RH, 1000 hours 40°C, 95% RH, 1000 hours	
Thermal Shock	MIL-STD-202, Method 107, -65°C to 125°C, 30 min. cycle, 10 cycles	
Vibration	MIL-STD-202, Method 201, (10 to 55 to 10 Hz, 1 min. cycle, 2 hrs each in X-Y-Z)	
Chemical Resistance	MIL-STD-202, Method 215	

# **Design Consideration**

Because of the fast rise-time of the ESD transient, proper placement of XTREME-GUARD<sup>™</sup> suppressors are a key design consideration to achieving optimal ESD suppression. The devices should be placed on the circuit board as close to the source of the ESD transient as possible. Install XTREME-GUARD<sup>™</sup> suppressors (connected from signal/data line to ground) directly behind the connector so that they are the first board-level circuit component encountered by the ESD transient.

## **Soldering Parameters**

Reflow Condition		Pb – Free assembly
Pre Heat	- Temperature Min (T <sub>s(min)</sub> )	150°C
	- Temperature Max (T <sub>s(max)</sub> )	200°C
	-Time (min to max) (t <sub>s</sub> )	60 – 180 seconds
Average ramp up rate (Liquidus Temp $(T_L)$ to peak		3°C/second max
T <sub>S(max)</sub> to T <sub>L</sub> - Ramp-up Rate		3°C/second max
Reflow	- Temperature (T <sub>L</sub> ) (Liquidus)	217°C
	- Temperature (t <sub>L</sub> )	60 – 150 seconds
Peak Temperature (T <sub>P</sub> )		260°C
Time within 5°C of actual peak Temperature (t <sub>p</sub> )		10 – 30 seconds
Ramp-down Rate		6°C/second max
Time 25°C to peak Temperature (T <sub>P</sub> )		8 minutes max



Based on IPC/JEDEC J-STD-020

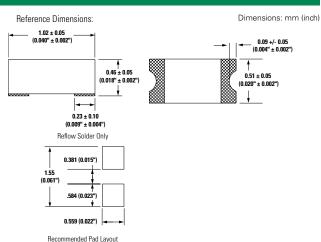
## Packaging

Part Number	Quantity & Packaging Code	Quantity	Packaging Option	Packaging Specification
XGD10402	KR	10000	Tape & Reel (7" reel)	EIA RS-481-1 (IEC 286, part 3)
XGD10603	MR	1000	Tape & Reel (7" reel)	EIA RS-481-1 (IEC 286, part 3)
XGD10603	NR	5000	Tape & Reel (7" reel)	EIA RS-481-1 (IEC 286, part 3)



#### **Dimensions**

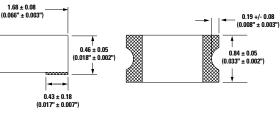
#### 0402 Device

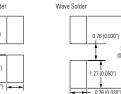


# 0603 Device Reference Dimensions: 1.68 ± 0.08 (0.066" ± 0.003")

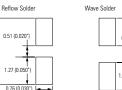
3.05 (0.120\*)

Dimensions: mm (inch)



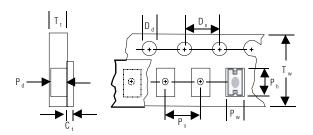


(0.130\*



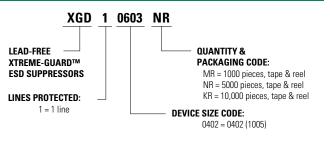
0402 Series (mm)	0603 Series (mm)		
0.05	0.05		
1.50	1.50		
4.00	4.00		
0.56	0.58		
1.14	1.85		
	(mm) 0.05 1.50 4.00 0.56		

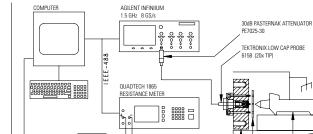
#### **Tape and Reel Specifications**



Description	0402 Series (mm)	0603 Series (mm)
C <sub>t</sub> - Cover tape thickness	0.05	0.05
D <sub>d</sub> - Drive hole diameter	1.50	1.50
D <sub>s</sub> - Drive hole spacing	4.00	4.00
P <sub>d</sub> - Pocket depth	0.56	0.58
P <sub>h</sub> - Pocket height	1.14	1.85
P <sub>s</sub> - Pocket spacing	2.00	4.00
P <sub>w</sub> - Pocket width	0.62	1.02
T <sub>t</sub> - Carrier tape thickness	0.65	0.65
T <sub>w</sub> - Carrier tape width	8.00	8.00

# **Part Numbering System**





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ESD TEST FIXTURE TEST BOARD W/ DUT ESD PULSE GENERATOR

RESISTANCE TEST FIXTURE

Typical Test Setup

Disclaimer Notice - Information furnished is believed to be accurate and reliable. However, users should independently evaluate the suitability of and test each product selected for their own applications. Littelfuse products are not designed for, and may not be used in, all applications. Read complete Disclaimer Notice at www.littelfuse.com/disclaimer-electronics.

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Authorized Distributor

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